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(12) **United States Design Patent**  
**Hosaka et al.**

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(54) **WAFER CARRYING-IN/OUT MACHINE**

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(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/297,744**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** ..... **15-99**

(52) **U.S. Cl.** ..... **D15/199; D13/182**

(58) **Field of Classification Search** ..... D13/182;  
D15/127, 140, 199; 118/500, 719; 250/307,  
250/310, 311; 414/217, 222.01, 935, 936,  
414/937

See application file for complete search history.

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**OTHER PUBLICATIONS**

U.S. Appl. No. 29/266,907, filed Oct. 2, 2006, Hosaka, et al.  
U.S. Appl. No. 29/297,744, filed Nov. 16, 2007, Hosaka, et al.

\* cited by examiner

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(57) **CLAIM**

The ornamental design for a wafer carrying-in/out machine,  
as shown and described.

**DESCRIPTION**

FIG. 1 is a top plan view of a wafer carrying-in/out machine  
or the like, showing our new design;

FIG. 2 is a left side elevational view thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a right side elevational view thereof;

FIG. 5 is a rear elevational view thereof;

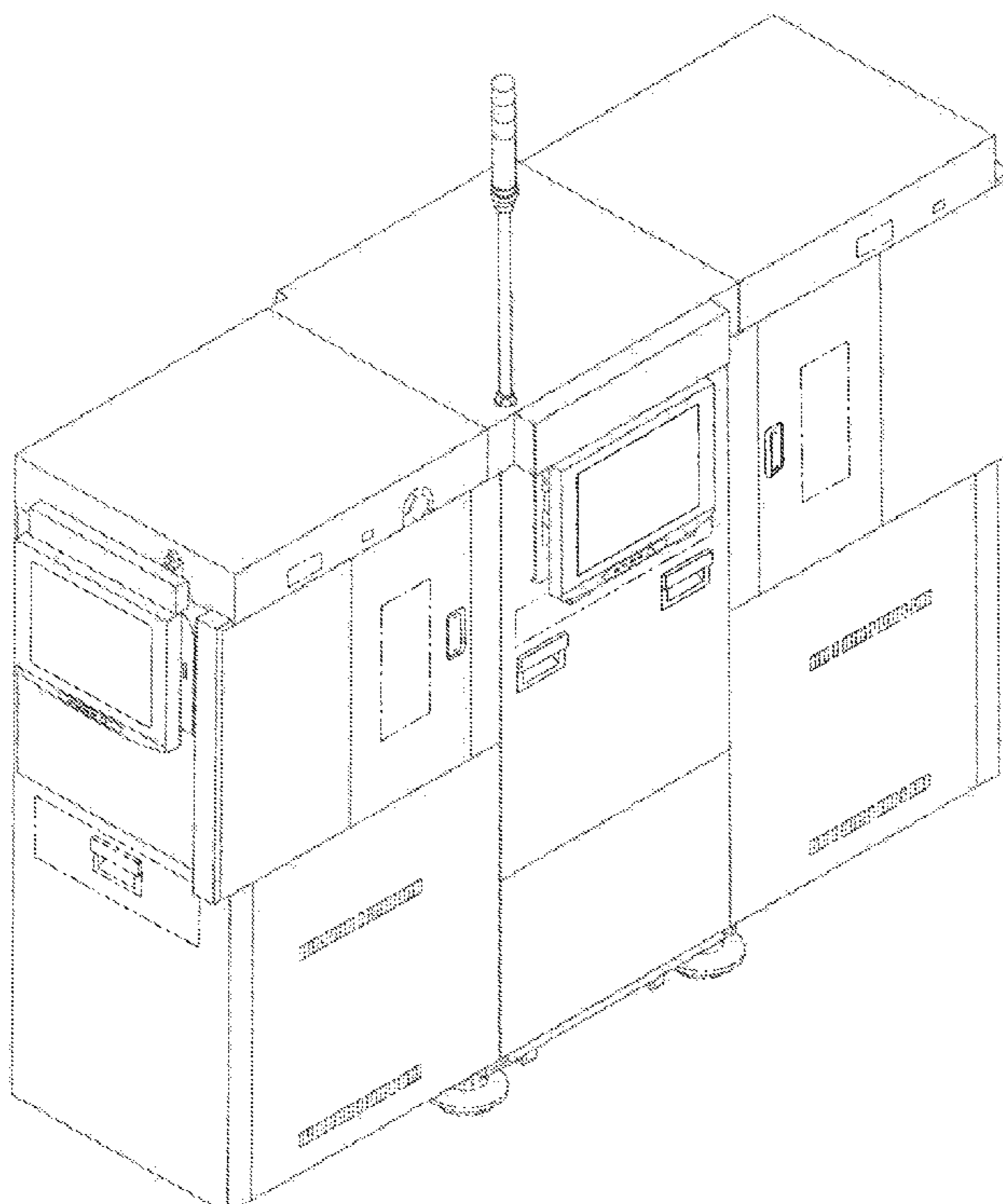
FIG. 6 is a top, front and left side perspective view thereof;

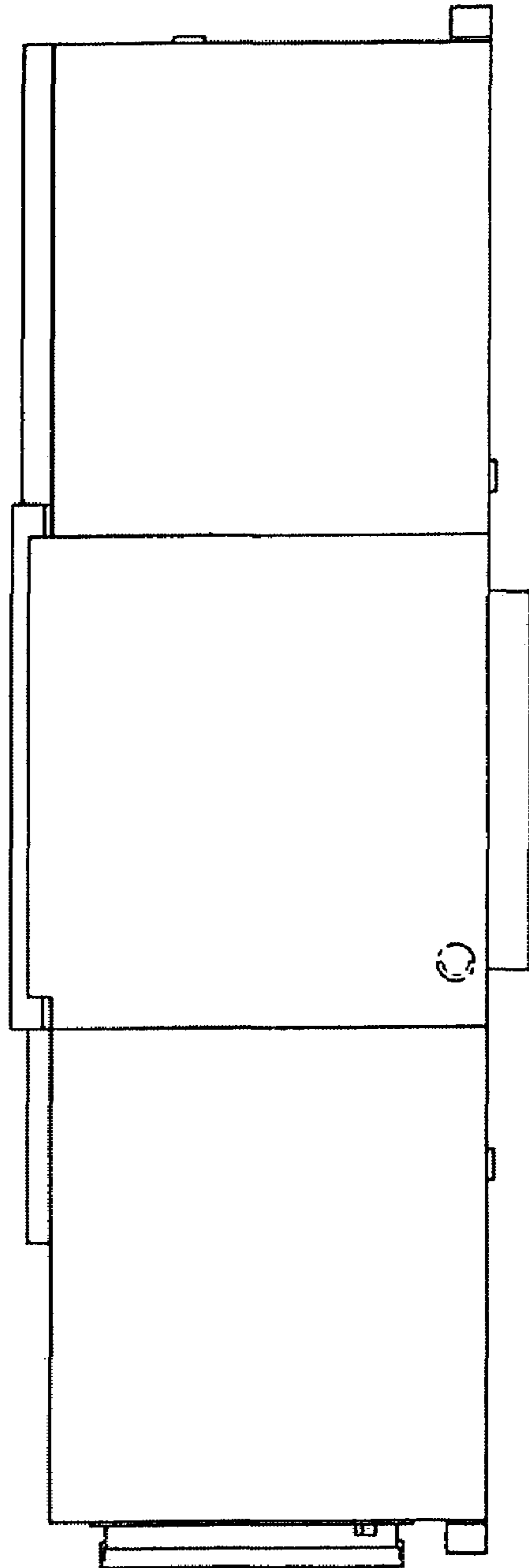
FIG. 7 is a front elevational view thereof; and,

FIG. 8 is a left side elevation thereof showing the wafer  
carrying-in/out machine when ready for shipment.

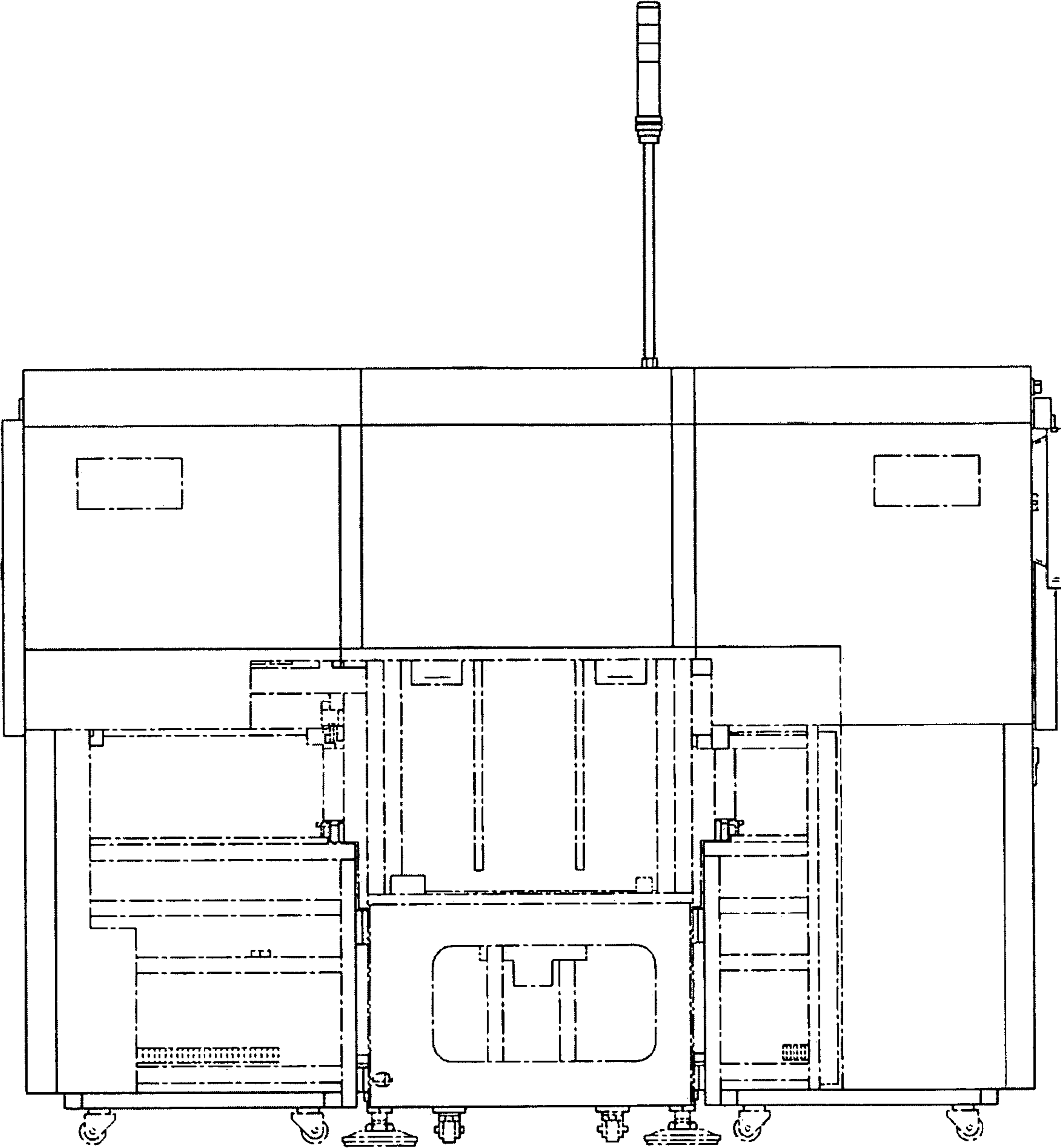
The phantom line showing in the figures is hereby disclaimed  
and forms no part of the claimed invention.

**1 Claim, 8 Drawing Sheets**

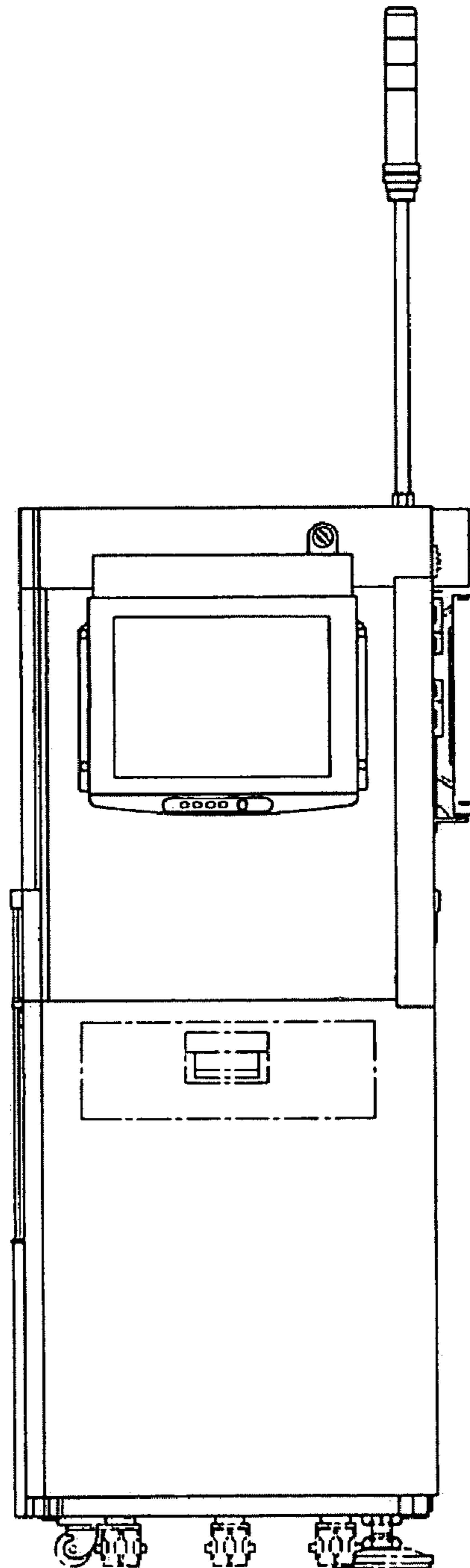




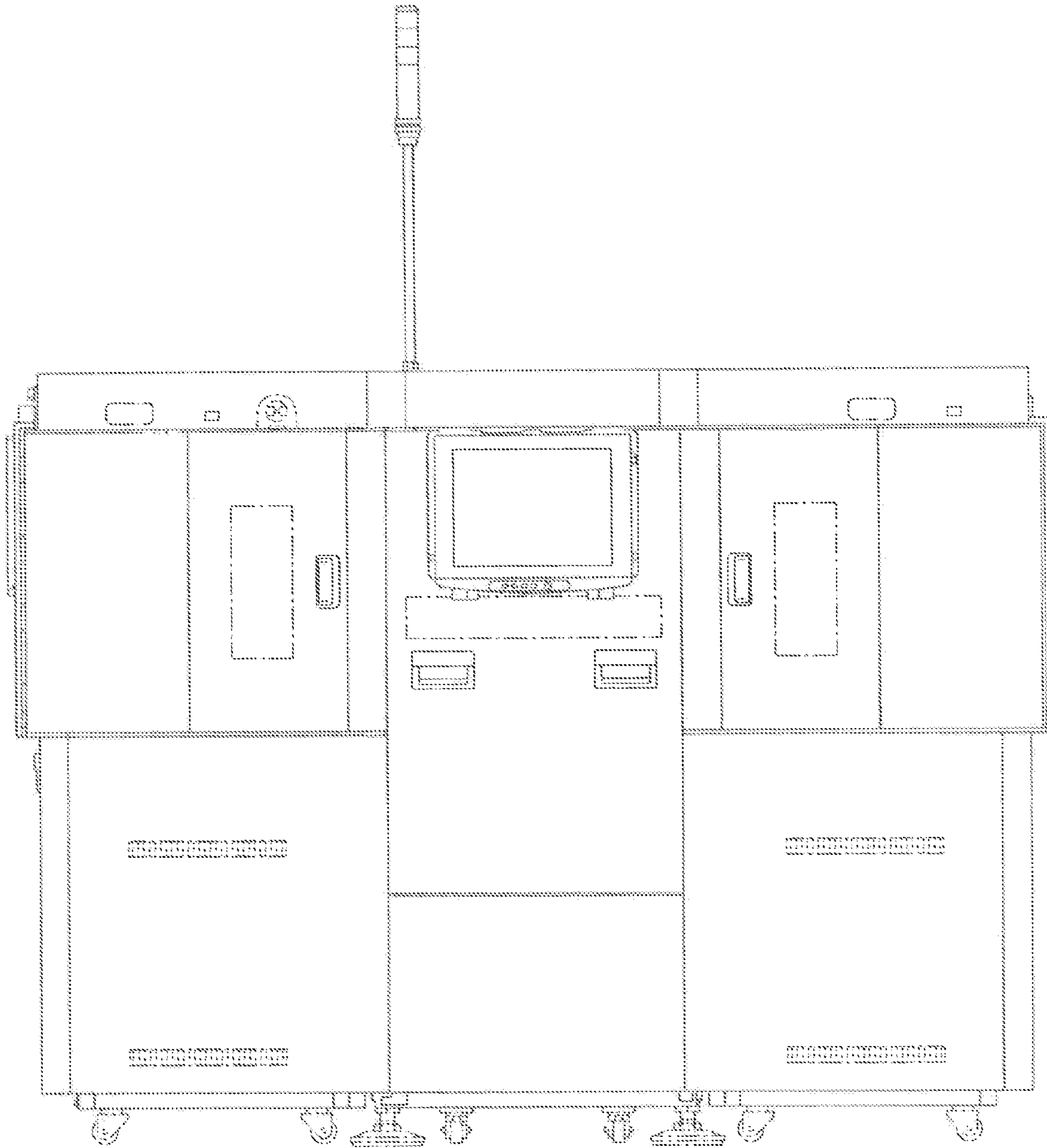
*Fig. 1*



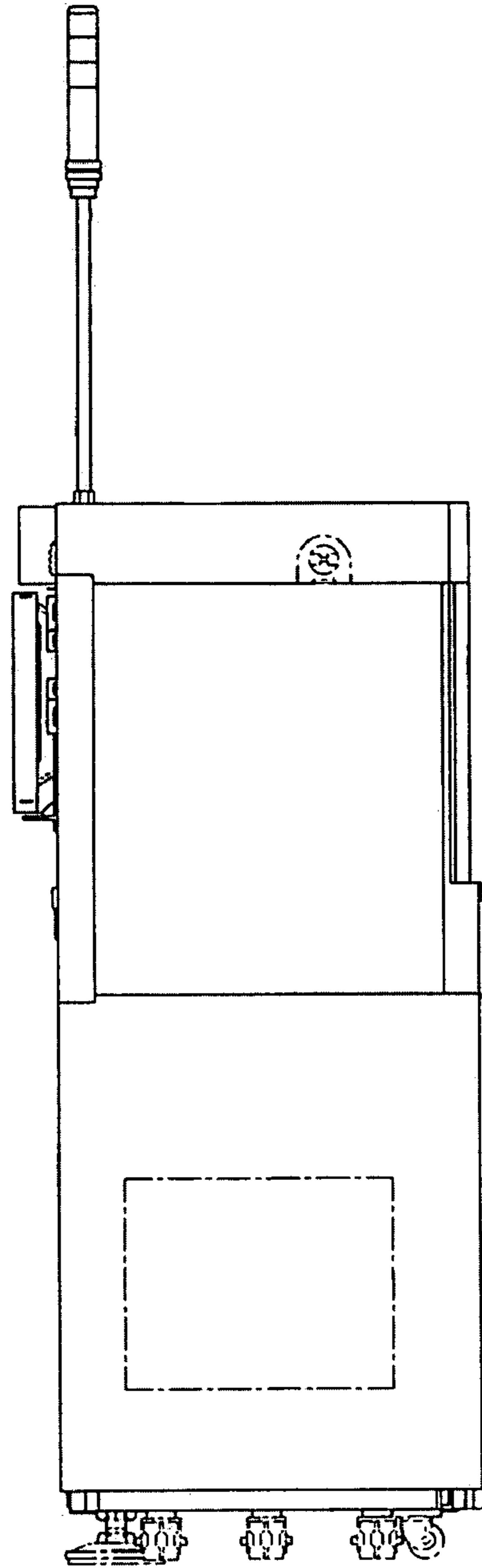
*Fig. 2*



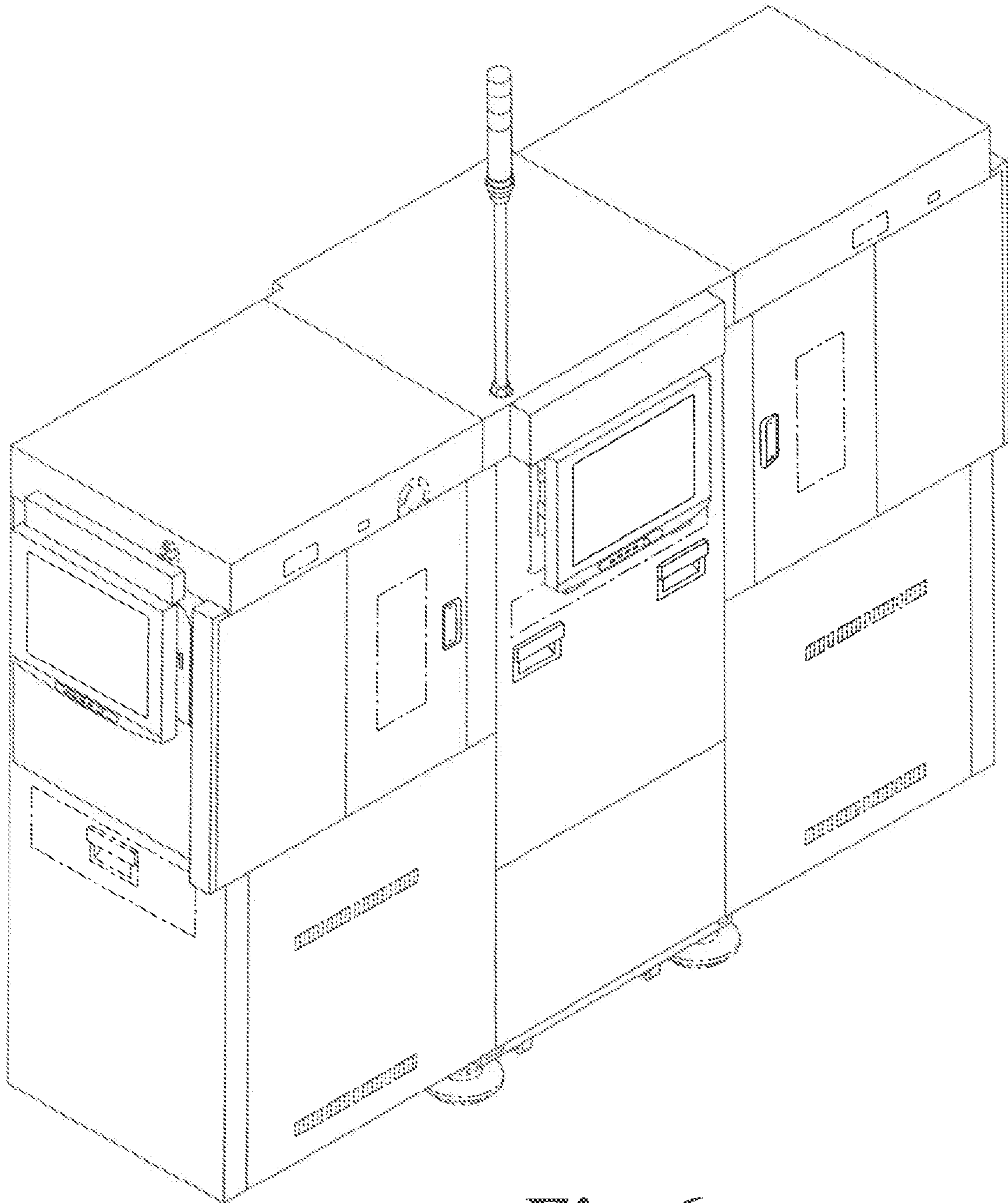
*Fig. 3*



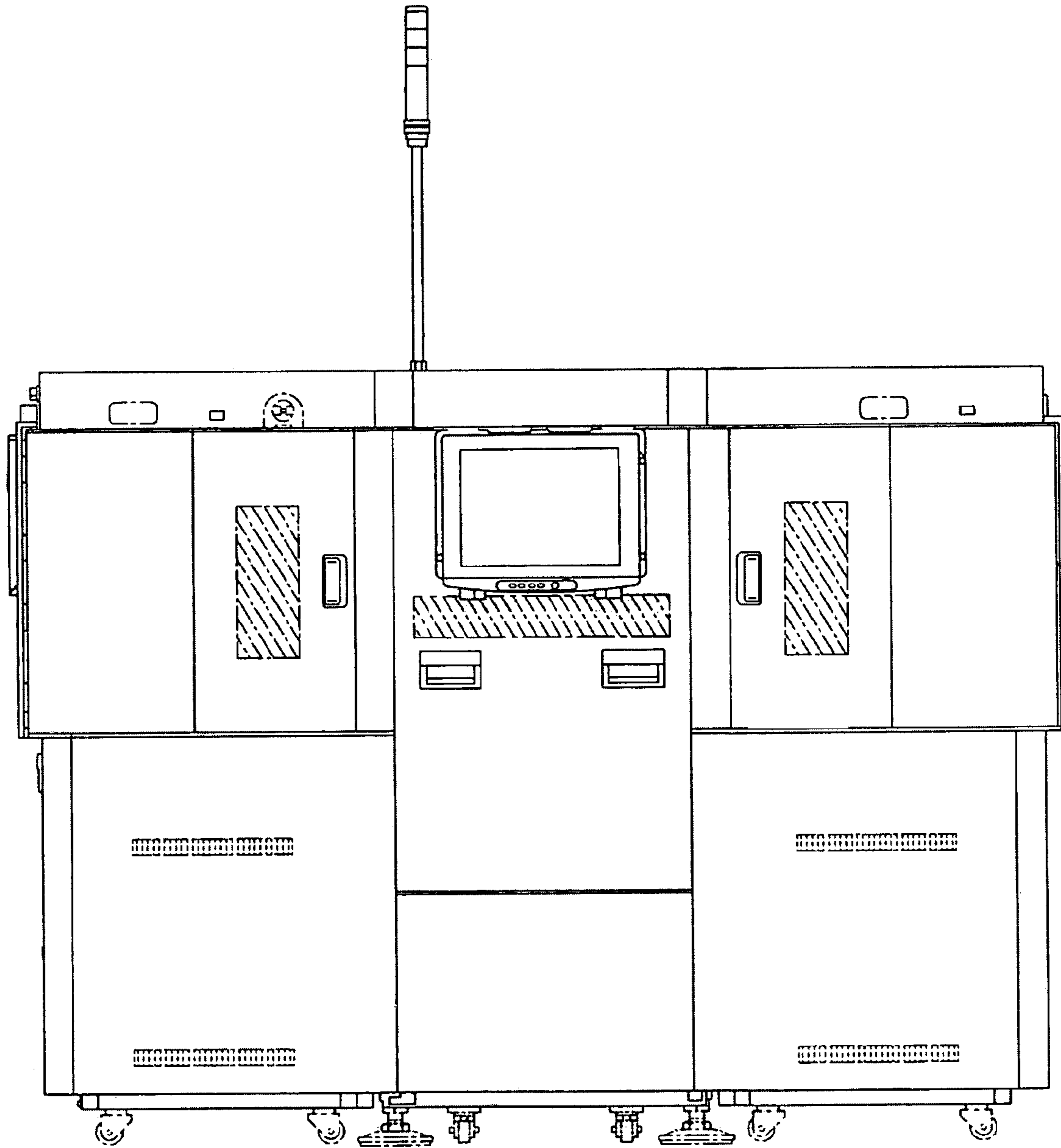
*Fig. 4*



*Fig. 5*

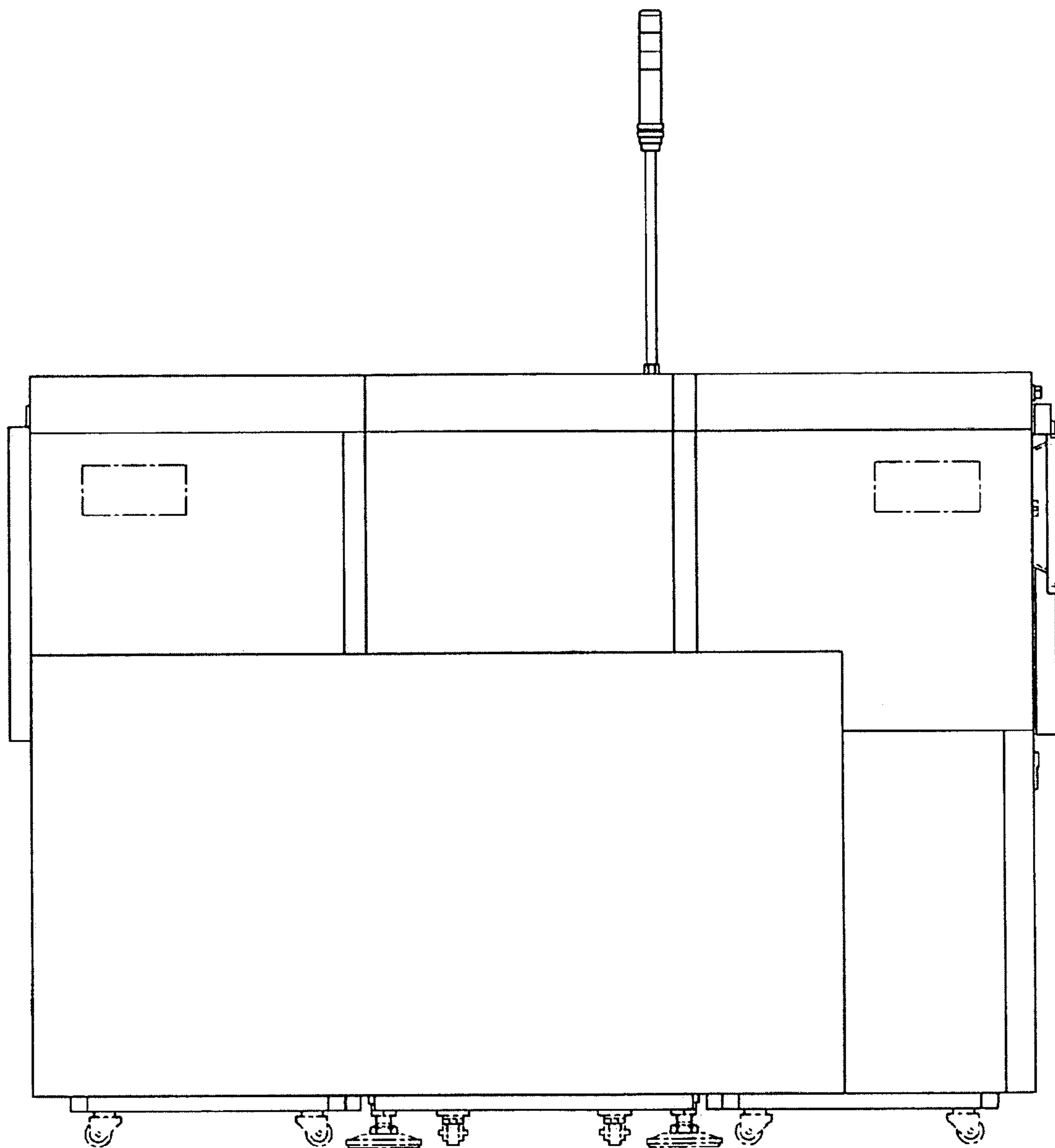


*Fig. 6*



*Fig. 7*





*Fig. 8*